HITANO ENTERPRISE CORP.

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Data Sheet

Customer:

Product: Safety Certified Multilayer Ceramic Chip Capacitors. FK / FH series

Size : 1206/1808/1812/2220/2211

Issued Date: 1-Mar.-2017

Edition: Ver. 1

Record of change

Date	Ver.	Description	Page
1-Mar.-2017	1		

VENDOR：

☐ **HITANO ENTERPRISE CORP.**

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MAKER：

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Taiwan, R.O.C

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1. Introduction

SAFETY CERTIFIED CAPACITORS are designed for surge or lightning immunity in modem facsimile and other equipments. The capacitors of series FK are class X1/Y2 compliant respectively.

The green type capacitors in FK series are manufactured by using environmentally friendly materials without lead or cadmium.

The terminations are composed of plated nickel and pure tin to feature the superior leaching resistance during soldering

2. Features

a. High reliability and stability.
b. Small size and high capacitance
c. RoHS compliant
d. Safety standard approval by
   EN132400:1994+A2+A3+A4,
   IEC60384-14:2013
   UL 60384-14(Ed 2.0)
e. Certificate number:
   R 50041666 & R 50359148 by TUV E231248
   by UL, E346791 by UL(FOWX2/8)
f. HALOGEN compliant

3. Application

a. Modem.
b. Facsimile.
c. Telephone.
d. Other electronic equipment for lighting or surge protection and isolation.

Type Approved
Safety
Regular Production
Surveillance
TÜVRheinland
CERTIFIED
www.tuv.com
ID 2000000000

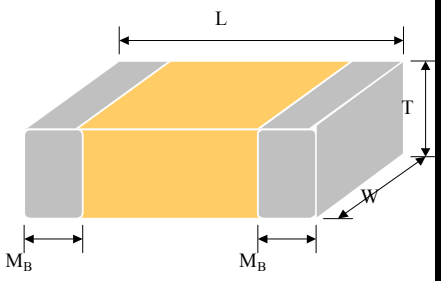
c UL us

4. How To Order

FK	08	N	100	J	502	E	F	G
Series	**Size**	**Dielectric**	**Capacitance**	**Tolerance**	**Rated voltage**	**Packaging**	**Thickness**	**Control Code**
Table1.	Table2	Table3	Table4	Table5	Table6	Table7	Table8	Table9

※ Reference document with No.11 reference table detail.

5. External Dimensions

Size Inch (mm)	L (mm)	W (mm)	Code / T (mm)	M_B (mm)	
1206 (3216)	3.30±0.30	1.60±0.20	See No.11 Reference Table 8	0.75±0.35	
1808 (4520)	4.50+0.5/-0.3	2.00±0.25		0.75±0.35	
1812 (4532)	4.50+0.5/-0.3	3.20±0.40		0.75±0.35	
2211 (5728)	5.70±0.40	2.80±0.30		0.85±0.35	
2220 (5750)	5.70±0.40	5.00±0.40		0.85±0.35	Fig.5-1 The outline of MLCC

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6. General Electrical Data

<table>
<tr><td>Dielectric</td><td colspan="2">C0G</td><td colspan="2">X7R</td></tr>
<tr><td>Size</td><td colspan="2">1808,1812, 2211</td><td>1808, 1812, 2211, 2220</td><td>1206</td></tr>
<tr><td>Rated voltage</td><td colspan="3">250VAC</td><td>2.5KVDC
2.0KVDC</td></tr>
<tr><td>Capacitance range</td><td colspan="2">X1/Y2 Class(Impulse 6KV)：4pF ~ 100pF
X1/Y2 Class(Impulse 5KV)：3pF ~ 720pF
X2 Class：3pF ~ 1000pF</td><td>X1/Y2 Class：100pF ~ 4700pF
X2 Class：150pF ~ 23000pF</td><td>1000pF</td></tr>
<tr><td>Capacitance tolerance</td><td colspan="2"><table><tr><td>Cap. Rang</td><td>Tolerance Spec.</td></tr><tr><td>Cap≤5pF</td><td>B (±0.1pF), C (±0.25pF)</td></tr><tr><td>5pF<Cap<10pF</td><td>C (±0.25pF), D (±0.5pF)</td></tr><tr><td>10pF≤Cap</td><td>F (±1%), G (±2%), J (±5%),K (±10%)</td></tr></table></td><td colspan="2">J (±5%)
K (±10%)
M (±20%)</td></tr>
<tr><td>Tan δ</td><td colspan="2"><table><tr><td>Cap. Rang</td><td>Q Spec.</td></tr><tr><td>Cap<30pF</td><td>Q≥400+20C</td></tr><tr><td>Cap≥30pF</td><td>Q≥1000</td></tr></table></td><td colspan="2">≤2.5%</td></tr>
<tr><td rowspan="3">Capacitance & Tan δ
Test Condition</td><td colspan="4">Measured at the condition of 30~70% related humidity</td></tr>
<tr><td colspan="2">for 25℃ at ambient temperature</td><td colspan="2">Preconditioning for Class II MLCC: Perform a heat treatment at 150±10℃ for 1 hour, then leave in ambient condition for 24±2 hours before measurement.</td></tr>
<tr><td colspan="2"><table><tr><td>Cap. Rang</td><td>Test Condition</td></tr><tr><td>Cap≤1000pF</td><td>1.0±0.2Vrms,
1.0MHz±10%</td></tr><tr><td>Cap>1000pF</td><td>1.0±0.2Vrms,
1.0kHz±10%</td></tr></table></td><td colspan="2">1.0±0.2Vrms, 1.0kHz±10%, at 25℃ ambient temperature.</td></tr>
<tr><td>Insulation resistance</td><td colspan="2">≥100GΩ or R•C≥ 1000Ω-F whichever is smaller</td><td colspan="2">≥10GΩ or R•C≥500Ω-F whichever is smaller</td></tr>
<tr><td>Operating temperature</td><td colspan="4">-55 to +125℃</td></tr>
<tr><td>Temperature coefficient</td><td colspan="2">±30ppm / ℃</td><td colspan="2">±15%</td></tr>
<tr><td></td><td colspan="4">Cu (or Ag)/Ni/Sn (lead-free termination)</td></tr>
</table>

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7.Capacitance Range

Class		X1/Y2(FK Series)								X2(FH Series)					
Rated Voltage		250Vac													2KVdc
															2.5KVdc
Certificated		TUV IEC60384-14 / UL-60384													UL-60950
DIELECTRIC		C0G				X7R				C0G		X7R			X7R
Cap	EIA Size	1808	1812	2211	2211	1808	1812	2211	2220	1808	1812	1808	1812	2220	1206
(pF)	Impulse	5KV			6KV	5KV				2.5KV					---
3	3R0	D								D					
3.3	3R3	D								D					
3.9	3R9	D								D					
4	4R0	D		F	F					D					
4.7	4R7	D		F	F					D					
5	5R0	D		F	F					D					
5.6	5R6	D		F	F					D					
6	6R0	D		F	F					D					
6.8	6R8	D		F	F					D					
7	7R0	D		F	F					D					
8	8R0	D		F	F					D					
8.2	8R2	D		F	F					D					
9	9R0	D		F	F					D					
10	100	D	C	F	F					D	C				
12	120	D	C	F	F					D	C				
15	150	D	C	F	F					D	C				
18	180	D	C	F	F					D	C				
22	220	D	C	F	F					D	C				
27	270	D	C	F	F					D	C				
33	330	D	C	F	F					D	C				
39	390	E	C	F	F					E	C				
47	470	E	C	F	F					E	C				
56	560	E	C	F	F					E	C				
68	680	E	C	F	G					E	C				
82	820	E	C	F	G					E	C				
100	101	F	C	F	H	E				F	C				
120	121	F	C	G		E				F	C				
130	131	F	C	G		E		E		F	C				

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7.Capacitance Range

Class		X1/Y2(FK Series)								X2(FH Series)					
Rated Voltage		250Vac													2KVdc
															2.5KVdc
Certificated		TUV IEC60384-14 / UL-60384													UL-60950
DIELECTRIC		C0G				X7R				C0G		X7R			X7R
Cap	EIA Size	1808	1812	2211	2211	1808	1812	2211	2220	1808	1812	1808	1812	2220	1206
(pF)	Impulse	5KV			6KV	5KV				2.5KV					---
150	151	F	C	G		E	E	E		F	C	E			
160	161	F	C	G		E	E	E	F	F	C	E			
180	181	F	C	G		E	E	E	F	F	C	E			
220	221	F	F	G		E	E	E	F	F	C	E			
270	271	F	F	G		F	E	E	F	F	C	E	E		
300	301		F	G		F	E	E	F	F	C	E	E		
330	331		F	G		F	E	E	F	F	C	E	E		
390	391		F	G		F	E	E	F	F	C	E	E		
470	471		F	G		F	E	F	F	F	C	E	E		
560	561			G		F	E	F	F	F	C	E	E		
680	681			G		F	F	F	F	F	F	E	E		
720	721			G		F	F	F	F	F	F	E	E		
820	821					F	F	F	F	F	F	E	E		
1000	102					F	G	G	F	F	F	F	E		C
1200	122							G	G			F	E		
1500	152							G	G			F	F		
1800	182							G	G			F	F		
2200	222							G	G			F	G		
2700	272								G				G		
3300	332								G				G		
3900	392								G				G		
4700	472								G				G		
5600	562												G		
6800	682														
10000	103													G	
12000	123													G	
15000	153													G	
18000	183													G	
22000	223													H	

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8.Reliability Test Conditions and Requirement

<table>
<tr><th>No.</th><th>Item</th><th>Standard Methods</th><th>Test Condition</th><th>Requirements</th></tr>
<tr><td>1.</td><td>Visual examination and Dimensions</td><td>IEC 60384-1
4.1</td><td>---</td><td>*No remarkable defect.
*Dimensions to confirm to individual specification sheet.</td></tr>
<tr><td>2.</td><td>Capacitance</td><td>IEC 60384-1
4.2.2</td><td>Class I: C0G
Cap≤1000pF, 1.0±0.2Vrms, 1MHz±10%
Cap>1000pF, 1.0±0.2Vrms, 1KHz±10%

Class II: (X7R)
1.0±0.2Vrms, 1kHz±10%</td><td>* Capacitance is within specified tolerance
* C_R means rated capacitance for conform to the E6 series of preferred values given in IEC 60063.</td></tr>
<tr><td>3.</td><td>Q/D.F. (Dissipation Factor)</td><td>IEC 60384-1
4.2.3</td><td></td><td><table><tr><td>Dielectric</td><td>Q/D.F.</td><td>Remark</td></tr><tr><td rowspan="2">Class I(C0G)</td><td>Q≥1000</td><td>Cap≥30pF</td></tr><tr><td>Q≥400+20C</td><td>Cap<30pF</td></tr><tr><td>Class II(X7R)</td><td>D.F. < 2.5%</td><td></td></tr></table></td></tr>
<tr><td>4.</td><td>Temperature Coefficient</td><td>IEC 60384-21/22
4.6</td><td>With no electrical load.<table><tr><td>T.C.</td><td>Operating Temp</td></tr><tr><td>C0G</td><td>-55~125℃ at 25℃</td></tr><tr><td>X7R</td><td>-55~125℃ at 25℃</td></tr></table></td><td><table><tr><td>T.C.</td><td>Capacitance Change</td></tr><tr><td>C0G</td><td>±30 ppm/℃</td></tr><tr><td>X7R</td><td>Within ±15%</td></tr></table></td></tr>
<tr><td>5.</td><td>Voltage proof (Dielectric Strength)</td><td>IEC 60384-14
4.2.1</td><td>To apply voltage:
X Capacitor: 1075Vdc (4.3U_R) Y Capacitor: 1500Vac
*Duration: 60 sec.
*The charge current shall not exceed 0.05A.
*The voltage shall be raised from the near zero to the test voltage a rate not exceeding 150V(r.m.s.)/sec.</td><td>*No evidence of damage or flash over during test</td></tr>
<tr><td>6.</td><td>Insulation Resistance</td><td>IEC 60384-21/22
4.5.3</td><td><table><tr><td>Rated vol.(V)</td><td>Apply Voltage</td><td>Charge Current</td><td>Charge Time</td></tr><tr><td>> 500</td><td>500VDC</td><td>≤ 50mA</td><td>60 sec</td></tr></table></td><td><table><tr><td>Dielectric</td><td>Requirements</td></tr><tr><td>Class I(C0G)</td><td>≥100GΩ or R•C≥1000Ω-F whichever is smaller</td></tr><tr><td>Class II(X7R)</td><td>≥10GΩ or R•C≥500Ω-F whichever is smaller</td></tr></table></td></tr>
<tr><td>7.</td><td>Solderability</td><td>IEC 60384-21/22
4.10</td><td>*Solder temperature: 235±5℃ (0201~1210)
*Solder temperature: 245±5℃ (1808~2225)
*Dipping time: 2±0.5 sec.</td><td>*75% min. coverage of all metalized area.</td></tr>
<tr><td>8.</td><td>Resistance to Soldering Heat</td><td>EC 60384-14
4.4
IEC 60384-21/22
4.9</td><td>* Solder temperature: 260±5℃
* Dipping time: 10±1 sec
* Preheating: 120 to 150℃ for 1 minute before immerse the capacitor in a eutectic solder.
* Measurement to be made after keeping at room temperature for 24c hrs (Class I)</td><td><table><tr><td>Dielectric</td><td>I.R</td><td>Cap Change</td><td>Q/D.F</td></tr><tr><td>Class I(C0G)</td><td>≥ 1GΩ</td><td>Within ±2.5% or ±0.25pF whichever is larger.</td><td rowspan="2">≤ 1.0 × Initial requirement</td></tr><tr><td>Class II(X7R)</td><td>≥ 1GΩ</td><td>within ±7.5%</td></tr></table></td></tr>
</table>

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8.Reliability Test Conditions and Requirement

<table>
<tr><th>No.</th><th>Item</th><th>Standard Methods</th><th>Test Condition</th><th>Requirements</th></tr>
<tr><td>9.</td><td>Temperature Cycle</td><td>IEC-60384-21/22
4.11</td><td>* Conduct the five cycles according to the temperatures and time
<table>
<tr><td>Step</td><td>Temp. (℃)</td><td>Time(min)</td></tr>
<tr><td>1</td><td>Min. operating temp.+0/-3</td><td>30±3</td></tr>
<tr><td>2</td><td>Room Temp.</td><td>2~3</td></tr>
<tr><td>3</td><td>Max. operating temp.+3/-0</td><td>30±3</td></tr>
<tr><td>4</td><td>Room Temp.</td><td>2~3</td></tr>
</table>
*Measurement to be made after keeping at room temperature for 24c hrs (Class I)</td><td>
<table>
<tr><td>T.C.</td><td>I.R.</td><td>Cap Change</td><td>Q/D.F</td></tr>
<tr><td>COG</td><td>Meet Initial value</td><td>Within ±2.5% or ±0.25pF whichever is larger.</td><td>≦1.0(Q)x Initial requirement</td></tr>
<tr><td>X7R</td><td></td><td>within ±7.5%</td><td>≦1.5(DF)x Initial requirement</td></tr>
</table>
</td></tr>
<tr><td>10.</td><td>Humidity (Damp Heat) Steady State</td><td>IEC 60384-14
4.12</td><td>* Test temp.: 40±2°C
* Humidity: 90~95% RH
* Test time: 500+24/-0hrs.
* Applied Voltage:250Vac.
* Measurement to be made after keeping at room temp. for 24±2 hrs (Class I) and 48±4 hrs (Class II)</td><td>* No remarkable damage.
<table>
<tr><td>T.C.</td><td>I.R.</td><td>Cap Change</td><td>Q/D.F</td></tr>
<tr><td>COG</td><td>Meet Initial value</td><td>Within ±2.5% or ±0.25pF whichever is larger.</td><td>≦1.0(Q)x Initial requirement</td></tr>
<tr><td>X7R</td><td></td><td>within ±7.5%</td><td>≦1.5(DF)x Initial requirement</td></tr>
</table>
</td></tr>
<tr><td>11.</td><td>Passive Flammability</td><td>IEC 60384-14
4.17
IEC 60384-1
4.38</td><td>* Volume sample: 21.56 mm3
* Flame exposure time: 5 sec Max.
* Category of flammability : C.</td><td>* Capacitor didn’t burn at all
(FH06X series not include)</td></tr>
<tr><td>12.</td><td>Active Flammability</td><td>IEC 60384-14
4.17
IEC 60384-1
4.38</td><td>* The capacitors applied UR (250Vac). Then each sample shall be subjected to 20 discharges from a tank capacitor, charge to a voltage that, when discharged, places Ui 2500V for X2, Ui 5000V for X1Y2 across the capacitor under test. The interval between successive discharges shall be 5 sec.</td><td>* The cheese cloth shall not burn with a flame.
(FH06X series not include)</td></tr>
<tr><td>13.</td><td>High Temperature Load (Endurance)</td><td>IEC 60384-14
4.14</td><td>* Impulse Voltage:
Each individual capacitor shall be subjected to a Vp = 5.0KV (X1Y2 Class Impulse 5KV) & Vp = 6.0KV (X1Y2 Class Impulse 6KV) impulse for three times before applied to endurance test.
*Test Temp.: 125±3°C
* Test time: 1000+48/-0 hrs.
* Applied Voltage:
X capacitor: 1.25UR (312.5Vac)
Y capacitor: 1.70UR (425Vac)
Once every hour the voltage shall be increased to 1000Vrms for 0.1 sec.
* Measurement to be made after keeping at room temp. for 24±2 hrs (Class I) and 48±4 hrs (Class II)
For FH06X series
* Test temp.: 125±3°C
* To apply voltage: 100% of rated voltage.
* Test time: 1000+24/-0 hrs.
* Measurement to be made after keeping at room temp. for 48±4 hrs.</td><td>* Appearance:
No mechanical damage.
* Cap change:
C0G within ±5% or ±0.5pF whichever is larger
X7R within ±20%
* D.F Value:
C0G ≤ 0.25%
X7R: ≤5.0%
* I.R. ≥1G_
* Dielectric strength satisfies the specified initial value</td></tr>
</table>

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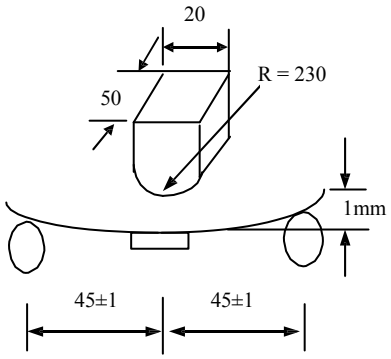
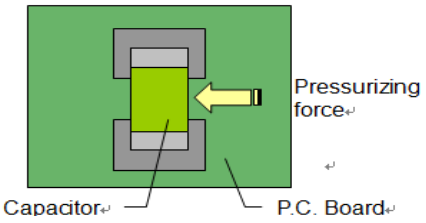
8.Reliability Test Conditions and Requirement

No.	Item	Standard Methods	Test Condition	Requirements
14.	**Resistance to Flexure of Substrate**	IEC 60384-21/22 4.8	* Capacitors mounted on a substrate. The board shall be bent 1mm with a rate of 1mm/sec. 	* No remarkable damage. T.C. | COG | Within ±3.0% or ±2pF whichever is larger X7R | within ±12.5% (This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test.)
15.	**Adhesive Strength of Termination**	IEC 60384-21/22 4.15 IEC 60384-1 4.13	*Capacitors mounted on a substrate. A force of 10N applied perpendicular to the place of substrate and parallel the line joining the center of terminations for 10±1 sec. 	*No remarkable damage or removal of the terminations.
16.	**Vibration**	IEC 60384-1 4.17	*Reflow solder the capacitors on P C. Board before test. *Vibration frequency: 10~55 Hz/min. *Total amplitude: 1.5mm *Repeat the conditions for 2 hours each in 3perpendicular directions.	* No remarkable damage. * Cap change and Q/D.F.: To meet initial spec.
17.	**Impulse Voltage**	IEC 60384-14 4.13	* X1: 4.0KV, X2: 2.5KV. * Y2: 5.0KV, * Number of impulse : 24 max.	*There shall be no permanent breakdown or flashover. (FH06X series not include)

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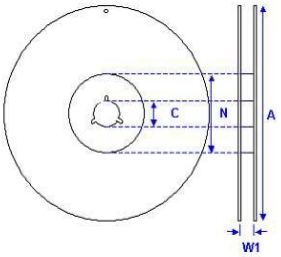
9.Package Dimensions and Quantity

Size	Thickness (mm)	Plastic tape	
		7" reel	13" reel
1206 (3216)	1.25±0.10	3000	10000
1808 (4520)	1.25±0.10	2000	10000
	1.60±0.20	2000	8000
	2.00±0.20	1000	6000
1812 (4532)	1.25±0.10	1000	-
	1.60±0.20	1000	-
	2.00±0.20	1000	-
	2.50±0.30	500	3000
2211 (5728)	1.60±0.20	1000	-
	2.00±0.20	1000	-
	2.50±0.30	500	-
	2.80±0.30	500	
2220 (5750)	2.00±0.20	1000	-
	2.50±0.30	500	2000

REEL DIMENSIONS		
Size	**1206,1808, 1812, 2211, 2220**	
Reel size	7"	
C	13.0+0.5/-0.2	
W1	12.4+2.0/-0	
A	178.0±0.10	
N	80.0±1.0	Fig.9.1 The dimension of plastic tape

9.1. Embossed Tape Dimensions

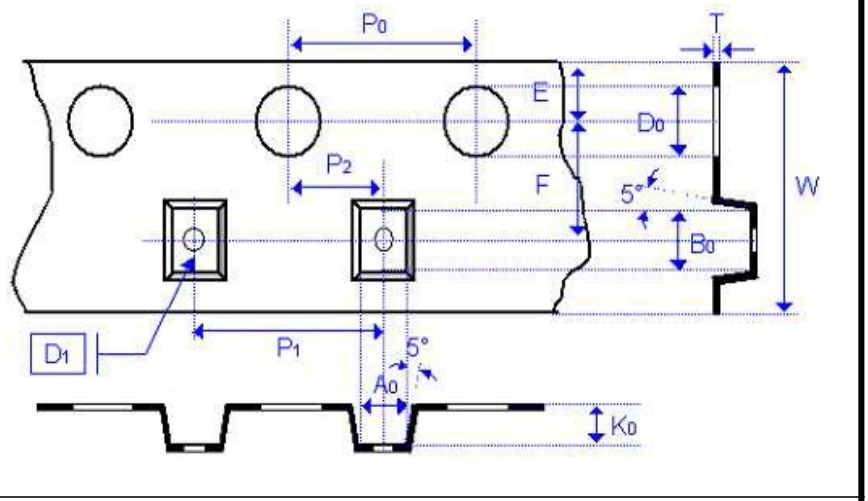


Fig.9.2 The dimension of plastic tape

Unit(mm)

Size	1206	1808		1812		2211		2220	
Chip Thickness	1.25±0.10	1.25±0.10 1.40±0.15 1.60±0.20	2.00±0.20	1.25±0.10 1.60±0.20 2.00±0.20	2.50±0.30	1.60±0.20 2.00±0.20	2.50±0.30 2.80±0.30	2.00±0.20	2.50±0.30
A_0	<2.00	<2.50	<2.50	<3.90	<3.90	<3.30	<3.30	<5.80	<5.80
B_0	<3.60	<5.30	<5.30	<5.30	<5.30	<6.50	<6.50	<6.50	<6.50
T	0.23±0.05	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05	0.30±0.10	0.30±0.10	0.30±0.10	0.30±0.10
K_0	<2.50	<2.50	<2.50	<2.50	<3.00	<2.50	<3.10	<2.50	<3.10
W	8.00±0.10	12.0±0.20	12.0±0.20	12.0±0.20	12.0±0.20	12.0±0.20	12.0±0.20	12.0±0.20	12.0±0.20
P_0	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
$10xP_0$	40.00±0.20	40.0±0.20	40.0±0.20	40.00±0.20	40.00±0.20	40.0±0.20	40.0±0.20	40.00±0.20	40.00±0.20
P_1	4.00±0.10	4.00±0.10	4.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10
P_2	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
D_0	1.50±0.10/-0	1.50±0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0	1.50+0.10/-0
D_1	1.00±0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50+/-0.10	1.50±0.10	1.50±0.10	1.50±0.10	1.50±0.10
E	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75+/-0.1	1.75±0.1	1.75±0.10	1.75±0.1	1.75±0.10

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9.Package Dimensions and Quantity

F	3.50±0.05	5.50±0.05	5.50±0.05	5.50±0.05	5.50+/-0.05	5.50±0.05	5.50±0.05	5.50±0.05	5.50±0.05

10.Application Notes

STORAGE

To prevent the damage of solderability of terminations, the following storage conditions are recommended: Indoors under 5 ~ 40℃ and 20% ~ 70% RH.

No harmful gases containing sulfuric acid, ammonia, hydrogen sulfide or chlorine.

Packaging should not be opened until the capacitors are required for use. If opened, the pack should be re-sealed as soon as is practicable. Taped product should be stored out of direct sunlight, which might promote deterioration in tape or adhesion performance. The product is recommended to be used within 12 months after shipment and checked the solderability before use.

HANDLING

Chip capacitors are dense, hard, brittle, and abrasive materials. They are liable to suffer mechanical damage, in the form of cracks or chips. Chip Capacitors should be handled with care to avoid contamination or damage. To use vacuum or plastic tweezers to pick up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

PREHEAT

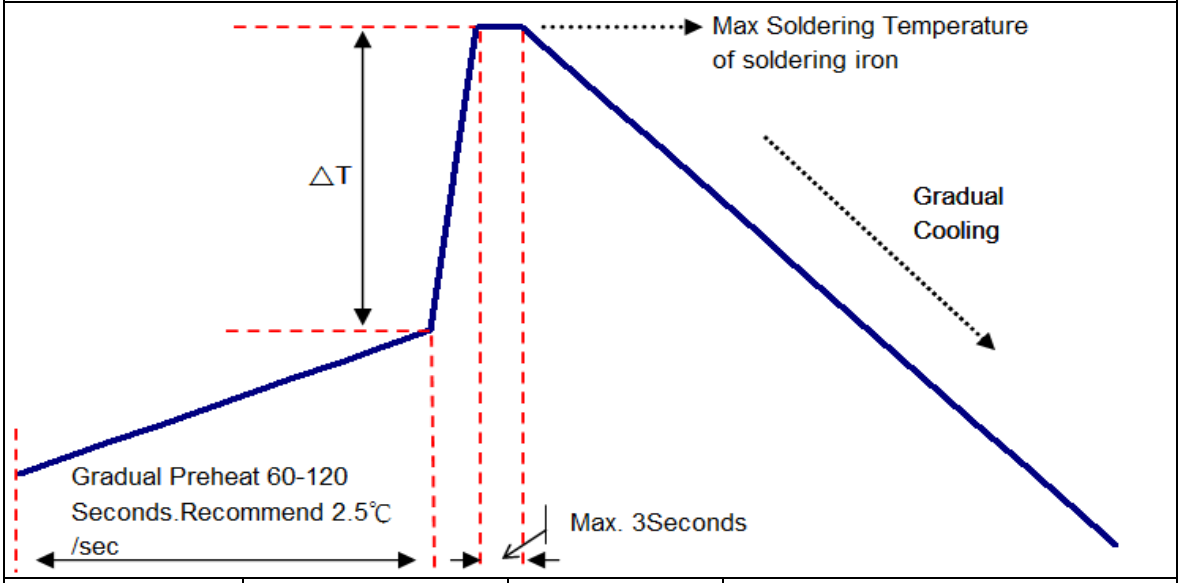
In order to minimize the risk of thermal shock during soldering, a carefully controlled preheat is required.
The rate of preheat should not exceed 3℃ per second.

SOLDERING

Use middy activated rosin RA and RMA fluxes do not use activated flux. The amount of solder in each solder joint should be controlled to prevent the damage of chip capacitors caused by the stress between solder, chips, and substrate.

a.) Hand soldering:

Hand Soldering Profile



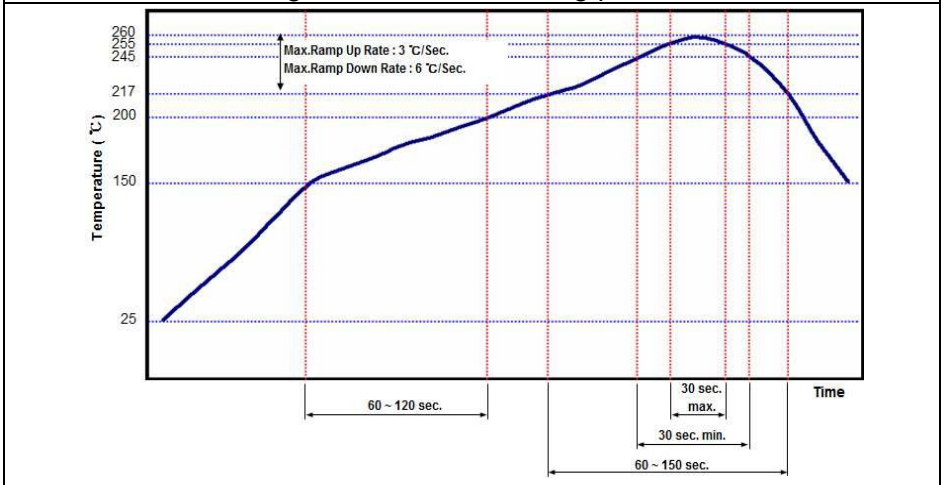
Chip Size	Pre-Heat temp.	△T	Max soldering iron temp.
≦1206	≧150 ℃	≦150 ℃	≦350 ℃
1210~2225	≧150 ℃	≦130 ℃	≦280 ℃

*Soldering iron tip diameter ≦ 1.0 mm and wattage max. 20W.
*The Capacitors shall be pre-heated and that the temperature gradient between the devices and the tip of the soldering iron.
*The required amount of solder shall be melted on the soldering tip.
*The tip of iron should not contact the ceramic body directly.
*The Capacitors shall be cooled gradually at room temperature after soldering.
*Forced air cooling is not allowed.

10.Application Notes

b.) Reflow soldering:

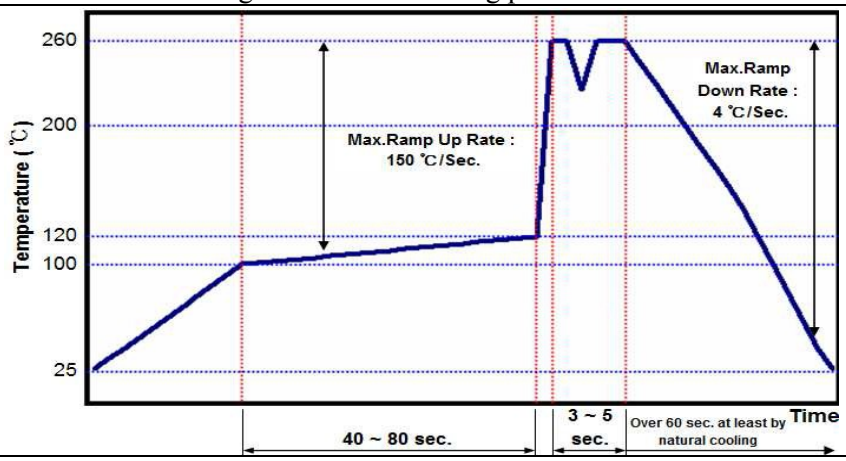
Fig.10.1 Reflow soldering profile



For Sn / Ag / Cu Series solder paste (Pb-Free)

c.) Wave soldering:

Fig.10.2 Wave soldering profile



For Sn / Ag / Cu Series solder paste (Pb-Free)

Soldering conditions:

Class I:

Size Inch (mm)	Dielectric	Capacitance	Condition	
			Wave	Reflow
0402(1005)	COG	All	X	O
0603(1608)	COG	All	O	O
0805(2012)	COG	All	O	O
1206(3216)	COG	All	O	O
≧1210(3225)	COG	All	X	O

Class II:

Size Inch (mm)	Dielectric	Capacitance	Condition	
			Wave	Reflow
0402(1005)	X7R	All	X	O
0603(1608) 0805(2012)	X7R	Cap.＜2.2μF	O	O
		Cap.≧2.2μF	X	O
1206(3216)	X7R	Cap.＜4.7μF	O	O
		Cap.≧4.7μF	X	O
0402(1005) 0603(1608)	X7R	Cap.＜4.7μF	O	O
		Cap.≧4.7μF	X	O
0805(2012)	X7R	All	X	O

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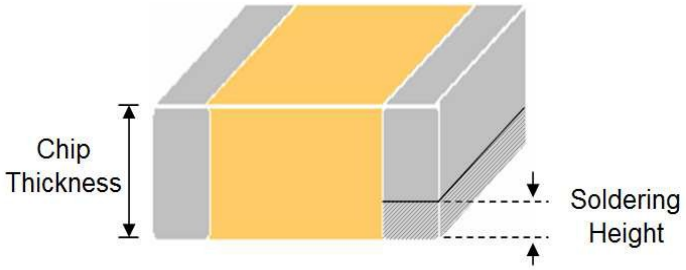
10.Application Notes

The solder climbing minimum height is suggesting to 25% of chip thickness or 500um whichever is less. (Reference from IPC-610E)



COOLING

After soldering, cool the chips and the substrate gradually to room temperature. Natural cooling in air is recommended to minimize stress in the solder joint.

CLEANING

All flux residues must be removed by using suitable electronic-grade vapor-cleaning solvents to eliminate contamination that could cause electrolytic surface corrosion. Good results can be obtained by using ultrasonic cleaning of the solvent. The choice of the proper system is depends upon many factors such as component mix, flux, and solder paste and assembly method. The ability of the cleaning system to remove flux residues and contamination from under the chips is very important.

11.Reference Table

Table 1	SERIES
Code	Description
FK	Safety X1 & Y2 series

Table 2	Size				
Code	Description	Code	Description	Code	Description
15	0402 (1005)	32	1210 (3225)	52	2211 (5728)
18	0603 (1608)	42	1808 (4520)	55	2220 (5750)
21	0805 (2012)	43	1812 (4532)	56	2225 (5763)
31	1206 (3216)	46	1825 (4563)		

Table 3	Dielectric Material Characteristics		
Code	Description	Code	Description
N	C0G	X	X7R
B	X5R	F	Y5V

Table 4	Table 4 Capacitance Rule Code		
Code	Description	Code	Description
R47	0.47pF	102	$102=10x10^{2}=1000pF$
0R5	0.5pF	104	$104=10x10^{4}=100nF$
100	$100=10x10^{0}=10pF$	106	$106=10x10^{6}=10\mu F$

Table 5	Tolerence				
Code	Description	Code	Description	Code	Description
A	±0.05 pF	I	-10% ~ 0%	Q	±0.03 pF
B	±0.10 pF	J	±5 %	Z	-20% ~ +80%
C	±0.25 pF	K	±10 %		
D	±0.50 pF	L	0% ~ +10%		
F	±1 %	M	±20 %		
G	±2 %	N	-5% ~ +10%		
H	±3 %	P	±0.02 pF		

Table 6	Rated voltage				
Code	Description	Code	Description	Code	Description
6R3	6.3VDC	201	200VDC	152	1500VDC
100	10VDC	251	250VDC	202	2000VDC
160	16VDC	401	400VDC	302	3000VDC
250	25VDC	501	500VDC	402	4000VDC
500	50VDC	631	630VDC	502	5000VDC
101	100VDC	102	1000VDC	602	6000VDC

Table 7	Packaging Type		
Code	Description	Code	Description
B	Bulk	T	Tray package
E	Tape and 7" Reel, Embossed Tape	P	Tape and 7" Reel, Paper Tape
K	Tape and 10" Reel, Embossed Tape	D	Tape and 10" Reel, Paper Tape
L	Tape and 13" Reel, Embossed Tape	G	Tape and 13" Reel, Paper Tape

Table 8	Thickness Description			unit(mm)	
Code	Description	Code	Description	Code	Description
A	0.60 ± 0.10	I	1.25 ± 0.20	Q	0.50 + 0.02/-0.05
B	0.8 + 0.15/-0.10	J	1.15 ± 0.15	R	3.10 ± 0.30
C	1.25 ± 0.10	K	0.50 ± 0.20	S	0.80 ± 0.07
D	1.40 ± 0.15	L	0.30 ± 0.03	T	0.85 ± 0.10
E	1.60 ± 0.20	M	0.95 ± 0.10	U	0.50 ± 0.10
F	2.00 ± 0.20	N	0.50 ± 0.05	V	0.20 ± 0.02
G	2.50 ± 0.30	O	3.50 ± 0.20	X	0.80 ± 0.10
H	2.80 ± 0.30	P	1.60 +0.3/-0.10	Z	0.25 ± 0.03

Table 9	Special Control Code
Code	Description
G	RoHS compliant
Q	Surface Coating(1206`2225)